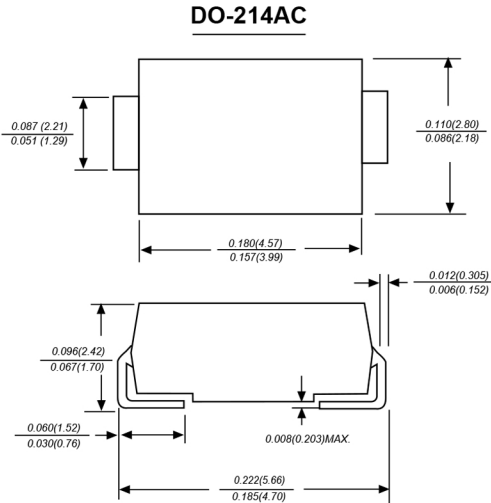


FEATURES

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals

MECHANICAL DATA

Case: JEDEC DO-214AC molded plastic body
Terminals: leads solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight : 0.058 grams



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	SS32	SS33	SS34	SS35	SS36	SS38	SS310	SS315	SS320	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	150	200	VOLTS
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	105	140	VOLTS
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	150	200	VOLTS
Maximum average forward rectified current at TL(see fig.1)	$I_{(AV)}$	3.0									Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	70.0									Amps
Maximum instantaneous forward voltage at 3.0A	V_F	0.55		0.70		0.85		0.95		Volts	
Maximum DC reverse current $T_A=25^\circ C$ at rated DC blocking voltage $T_A=100^\circ C$	I_R	0.5						1.0		mA	
Typical junction capacitance (NOTE 1)	C_J	500			300				pF		
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	55.0				62.0				°C/W	
Operating junction temperature range	T_J	-65 to +125			-65 to +150					°C	
Storage temperature range	T_{STG}	-65 to +150									°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

